Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.018”**



**.018”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: E = .003 B = .0025”**

**Backside Potential: COLLECTOR**

**APPROVED BY: DK DIE SIZE .018” X .018” DATE: 11/15/21**

**MFG: SEMICOA THICKNESS .010” P/N: 2N930A**

**DG 10.1.2**

#### Rev B, 7/1